

EDGE RING FOR A THERMAL PROCESSING CHAMBER

BACKGROUND

Field

[0001] Embodiment of the present invention generally relates to a method and apparatus for fabricating devices on a substrate. More particularly, embodiments of the present invention provide a substrate supporting ring to support a substrate around the edge region in a processing chamber.

Description of the Related Art

[0002] In the processing of substrates, such as semiconducting wafers and display panels, a substrate is placed on a support in a process chamber while suitable processing conditions are maintained in the process chamber. For example, a substrate can be heated in a controlled heating cycle to be thermally processed. During a thermal process, a substrate may be supported by a supporting structure, such as an edge ring, around the edge region while radiant energy source disposed above or below the substrate projects thermal energy towards the substrate.

[0003] Figure 1A schematically illustrates a sectional view of a traditional edge ring 101 used in a thermal processing chamber. The edge ring 101 has an inner diameter slightly smaller than an outer diameter of a substrate 102 being processed. During processing, the substrate 102 is disposed on a supporting surface 105 of the edge ring 101 so that the edge ring 101 contacts and supports the substrate 102 by an outer edge region 104. Thermal energy 103 may be directed to the substrate 102 below the substrate 102 and the edge ring 101 to heat the substrate 102.

[0004] However, the traditional edge ring 101 as shown in Figure 1A sometimes cause the temperature non-uniformity around the outer edge region 104 on the substrate 102. The temperature non-uniformity becomes

more pronounced when the substrate 102 is heated at a rapid rate. Figure 1B schematically illustrates temperature variations around the outer edge region 104 of a substrate during heating. In Figure 1B, the x-axis indicates azimuthally locations in an outer edge of a substrate denoted by 0 to 360 degrees. The y-axis indicates a temperature variation from an average temperature in Celsius degrees. Each curve 110, 111 represents a measurement of a substrate during rapid heating. As shown in Figure 1B, the temperature variation around the edge region of a substrate can be up to 8 degrees Celsius.

[0005] Therefore, there is a need for an improved substrate support for supporting a substrate around the edge region in a processing chamber.

SUMMARY

[0006] Embodiments of the present invention generally provide apparatus and methods for processing a substrate. More particularly, embodiments of the present invention provide an edge ring for supporting a substrate in a processing chamber.

[0007] One embodiment of the present invention provides an edge ring for supporting a substrate in a processing chamber. The edge ring includes a ring shaped body defined by an inner edge, an outer edge, an upper side and a lower side, wherein the inner edge and outer edge are concentric about a central axis. the edge ring also includes a lip extending radially inward from the inner edge of the ring shaped body. At least a portion of an upper surface of the lip is configured to support a substrate around an outer edge of the substrate so that the substrate is substantially parallel to a major plane that is perpendicular to the central axis. The edge ring also includes one or more surface area increasing structures formed out at least one or the upper side or lower side of the ring shaped body.

BRIEF DESCRIPTION OF THE DRAWINGS

[0008] So that the manner in which the above recited features of the present invention can be understood in detail, a more particular description of the invention, briefly summarized above, may be had by reference to embodiments, some of which are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only typical embodiments of this invention and are therefore not to be considered limiting of its scope, for the invention may admit to other equally effective embodiments.

[0009] Figure 1A is a schematic sectional view of a traditional edge ring.

[0010] Figure 1B illustrates temperature variation on a substrate during heating when supported by a traditional edge ring.

[0011] Figure 2A is a sectional view of an edge ring according to one embodiment of the present invention.

[0012] Figure 2B is a partial sectional perspective view of the edge ring of Figure 2A.

[0013] Figure 2C is a partial sectional perspective view showing a bottom side of the edge ring of Figure 2A.

[0014] Figure 2D is a top view of the edge ring of Figure 2A.

[0015] Figure 2E is a bottom view of the edge ring of Figure 2A.

[0016] Figures 3A-3G schematically illustrate edge rings according to embodiments of the present invention.

[0017] Figures 4A-4D schematically illustrate edge rings for having an upper energy receiving surface according to embodiments of the present invention.

[0018] Figure 5 is a schematic sectional view of a processing chamber according to one embodiment of the present invention.

[0019] Figure 6 includes plots showing performance comparison between traditional edge ring and edge rings according to embodiments of the present invention.

[0020] To facilitate understanding, identical reference numerals have been used, where possible, to designate identical elements that are common to the figures. It is contemplated that elements disclosed in one embodiment may be beneficially utilized on other embodiments without specific recitation

DETAILED DESCRIPTION

[0021] Embodiments of the present invention provide apparatus and methods for fabricating devices on a substrate. More particularly, embodiments of the present invention provide an edge ring for supporting a substrate during thermal processing with improved temperature uniformity.

[0022] Embodiments of the present invention provide an edge ring for supporting a substrate with increased temperature uniformity. More particularly, embodiments of the present invention provide an edge ring having one or more surface area increasing structures formed on an energy receiving surface of the edge ring. The surface area increasing structure increases the ratio of exposed surface area and mass in the edge ring, thus, reducing radial temperature gradient during heating. The added mass of the surface area increasing structure also improves azimuthal thermal conductivity of the edge ring. Therefore, the edge ring according to embodiment of the present invention reduces azimuthal and radial deformation of the edge ring and improve uniformity of thermal exchange between the edge ring and the substrate, thus improves processing uniformity.

[0023] Embodiments of the present invention also provides an edge having a chamber contacting surface located on a plane close to a plane including

the center of gravity of the edge ring. But positioning the chamber contacting surface at a level close to the center of gravity, the edge ring is supported at a level close to the center of gravity, thus reducing and controlling the bulking of the edge ring during processing.

[0024] Figure 2A is a sectional view of an edge ring 200 according to one embodiment of the present invention. The edge ring 200 is configured to support a substrate 202 during processing in a chamber. Generally, the edge ring 200 is disposed on a chamber component, such as a ring support 201, and is configured to contact the substrate 202 by an edge region 204 and allow the majority of the substrate 202 exposed to radiant energy 206.

[0025] The edge ring 200 includes a ring shaped body 210. The ring shaped body 210 is defined by an upper surface 212, a lower surface 214, an inner edge 216 and an outer edge 218. The inner edge 216 and the outer edge 218 may be concentric circles about a central axis 232. The inner edge 216 may have an inner radius 220 and the outer edge 218 has an outer radius 222. In one embodiment, the ring shaped body 210 has a major plane 234 perpendicular to the central axis 232.

[0026] A lip 224 extends radially inward from the inner edge 216 of the ring shaped body 210. The lip 224 has an upper surface 226 configured to support the substrate 202 by the edge region 204. The lip 224 is configured to position the substrate 202 substantially parallel to the major plane 234. The lip 224 forms a central opening 228 concentric to the inner edge 216 with a radius 230 from the central axis 232. The central opening 228 exposes the majority of a back surface 208 of the substrate 202.

[0027] In one embodiment, a fin 236 formed on the lower surface 214. The fin 236 to reduce temperature gradient from the outer edge 218 to the inner edge 216 and the lip 224. The fin 236 increases the surface area of the lower surface 214. In one embodiment, the fin 236 is a thin wall extending vertically from the lower surface 214. By being thin, the fin 236 increases

surface areas of the lower surface 214 without greatly increasing the mass of the edge ring 200. By increasing surface area of the lower surface 214, the fin 236 increases the rate of the edge ring 200 to draw thermal energy from the environment, thus, reducing temperature gradient in the edge ring 200 when the edge ring 200 is rapidly heated by the radiant energy 206.

[0028] In one embodiment, the fin 236 is a continuous circular wall concentric to the outer edge 218 and the inner edge 216, and the central opening 228. The fin 226 may be positioned between the outer edge 218 and the inner edge 216. The fin 236 has a radius 238 from the central axis 232. The radius 238 of the fin 236 may be controlled to adjust the radial temperature gradient or temperature profile of the edge ring 200, thus, reduce deformation of the edge ring 200 during heating. In one embodiment, the radial temperature gradient may be reduced by moving the fin 236 towards the inner edge 216.

[0029] Being continuous, the fin 236 also increases the stiffness of the edge ring 200, and further reduces deformation along radial direction and along azimuthal direction. Being continuous, the fin 236 also increases azimuthal thermal conductivity of the edge ring 200, thus, improve uniformity and reduce deformation.

[0030] In one embodiment, the edge ring 200 includes a positioning rim 240 extending from the ring shaped body 210 near the outer edge 218. The positioning rim 240 is configured to securely mount the edge ring 200 on a chamber component, such as a supporting ring 201 shown in dotted lines in Figure 2A.

[0031] In one embodiment, a bottom surface 242 of the rim is configured to contact the supporting ring 201 and receive support from the processing chamber. In one embodiment, the bottom surface 242 is a substantially planar and is positioned vertically in close proximity to the center of gravity 244 of the edge ring 200. As shown in Figure 2A, a plane 246 parallel to the

major plane 234 passes the center of gravity 244. The bottom surface 242, which receives supports from the chamber, is at a distance 248 from the plane 246. In one embodiment, the distance 248 is about 0.75 mm or less. The bottom surface 242 may be above or below the center of gravity 244 for less than 0.75mm.

[0032] According to embodiment of the present invention, by positioning the edge ring supporting surface vertically close to the center of gravity 244, deformation of the edge ring, such as bulking. According to one embodiment of the present invention, the direction of edge ring bulking can be adjusted by supporting the edge ring 200 on a plane above or below the center of gravity 244.

[0033] In one embodiment, the edge ring 200 is configured to support the substrate 202 while the substrate 202 is exposed to radiant energy 206 projected towards the backside 208 of the substrate 202. Both of the edge ring 200 and the substrate 202 are heated by the radiant energy 206. The edge region 204 of the substrate 202 is shadowed from the radiant energy 206 by the lip 224 of the edge ring 200. The edge region 204 is heated by direct thermal exchange with the lip 224 of the edge ring 200.

[0034] The surface area increasing structure, such as the fin 236 increases the exposed surface of edge ring 200, thus, increasing thermal conductivity, reducing temperature gradient, and ultimately reducing deformation in the edge ring 200. The position of the supporting surface 242 which is close to the center of gravity 244, reduces bulking of the edge ring 200, thus also reduce deformation of the edge ring. Because of the reduced deformation of the edge ring 200, the lip 224 of the edge ring 200 and the edge region 204 of the substrate 202 maintains solid direct contact around the entire edge region 204, thus, achieves uniform heating in the edge region 204.

[0035] Figure 2B is a partial sectional perspective view of the edge ring 200. Figure 2C shows the edge ring 200 being supported by the supporting

ring 201 by the bottom surface 242 of the positioning rim 240. Figure 2D is a top view of the edge ring 200. Figure 2E is a bottom view of the edge ring 200.

[0036] The edge ring 200 may be formed from a suitable material according to the material of the substrate 202 being processed. For example, the edge ring 200 may be formed from a material having a similar thermal capacity as the material of the substrate 202. For example, the edge ring 200 may be formed from a silicon carbide material for processing a silicon substrate. The edge ring 200 may be formed by sintering a powder material then machining to dimension. Details about the material and method for forming the edge ring can be found in United States Patent No. 6,888,104, US patent No. 7,127,367, which are incorporated herein by reference.

[0037] Embodiments of the provide an edge ring with surface area increasing structures formed on a surface that is configured to face a radiant energy source during a thermal processing. In one embodiment, the ratio of edge ring surface area that is exposed to a radiant energy source and the mass of the edge ring may be above about 0.55 meters squared per kilogram. In another embodiment, the ratio of exposed area and the mass may be above about 0.70 meters squared per kilogram. In another embodiment, the ratio of exposed area and the mass may be between about 0.7 to about 1.0 meters squared per kilogram.

[0038] Various factors may be considered to improve or modify the edge ring according to process requirements. Exemplary factors include but not limited to the ratio of exposed area and the mass of the edge ring, the outer diameter of the edge ring, the relative position of a supporting surface to the center of gravity, thermal conductivity along the radial direction, thermal conductivity along azimuthal direction, and stiffness of the edge ring.

[0039] Figures 3A-3G are partial sectional views of edge rings according to embodiments of the present invention. The edge rings shown in Figures 3A-

3G are configured to support a substrate while the substrate being heated from a radiant energy from disposed below the substrate and the edge ring.

[0040] Figure 3A is a partial schematic sectional view of an edge ring 310 for supporting a substrate 302 while mounted on a supporting ring 301. The edge ring 310 is similar to the edge ring 200 except the edge ring 310 is supported by a bottom surface 312 of a ring shaped body 311.

[0041] Figure 3B is a partial schematic sectional view of an edge ring 320. The edge ring 320 is similar to the edge ring 200 except the edge ring 320 includes a fin 323 positioned at an inner edge 322 of the ring shaped body 321. A lip 324 for supporting the substrate extends from the fin 324.

[0042] Figure 3C is a partial schematic sectional view of an edge ring 330. The edge ring 330 is similar to the edge ring 320 except the edge ring 330 is supported by a bottom surface 332 of a ring shaped body 331.

[0043] Figure 3D is a partial schematic sectional view of an edge ring 340. The edge ring 340 is similar to the edge ring 200 except the edge ring 340 includes a lip 344 that is tilted at an angle 342 from a horizontal plane 341. In one embodiment, the angle is about 10 degrees. In one embodiment, the location of supporting surface 343 may be adjusted relative to the center of gravity so that the lip 344 bulks to be substantially horizontal during processing.

[0044] Figure 3E is a partial perspective view of an edge ring 350. The edge ring 350 is similar to the edge ring 200 except the edge ring 350 a plurality of discrete fins 351. The discrete fins 351 further increase the exposed surface area.

[0045] Figure 3F is a partial schematic sectional view of an edge ring 360. The edge ring 360 is similar to the edge ring 200 except the edge ring 360 includes two fins 361, 362 concentrically arranged. Two fins further increases exposed surface area and stiffness of the structure.

[0046] Figure 3G is a partial schematic sectional view of an edge ring 370. The edge ring 370 is similar to the edge ring 200 except the edge ring 370 includes a lip 371 having a raised portion 372. The raised portion 372 has an upper surface 373 for contacting the substrate 302. The raised portion 372 may be one continuous structure, or a plurality of discrete structures.

[0047] Even though, fins are illustrated in the above examples, surface area increasing structures may have any suitable form.

[0048] Figures 4A-4D schematically illustrate edge rings for having an upper energy receiving surface according to embodiments of the present invention.

[0049] Figure 4A shows an edge ring 410 having a fin 412 extending from an upper surface 413 of the ring shaped body 411. The edge ring 410 is configured for supporting a substrate 402 while being heated by a radiant energy source 403 disposed above. The edge ring 410 includes a lip 414 for supporting the substrate 402. In one embodiment, a plurality of pads 415 is raised from the lip 414 for contacting the substrate 402.

[0050] Figure 4B shows an edge ring 420 having an upwardly extending fin 422 disposed near an inner edge 423 of a ring shaped body 421. A lip 424 extends from the fin 422.

[0051] Figure 4C shows an edge ring 430 having an upwardly extending fin 432 and a tilted lip 433.

[0052] Figure 4D shows an edge ring 440 having an upper fin 441 and a lower fin 442. The edge ring 440 is suitable when radiant sources are positioned both above and below the substrate and the edge ring.

[0053] Figure 5 is a schematic sectional view of a processing chamber 500 according to one embodiment of the present invention.

[0054] The processing chamber 500 includes a chamber body 502 defining a processing volume 504. A window 506 is formed on a bottom side of the chamber body 502. The window 506 may be formed from quartz. A radiant energy source 508 is disposed below the window 506. The radiant energy source 508 is configured to direct radiant energy towards the processing volume 504. In one embodiment, the radiant energy source 508 includes a plurality of lamps. A reflection plate 510 is disposed on an upper wall 512 of the chamber body 502 inside the processing volume 504. A plurality of sensors 524 may be disposed through the reflection plate 510.

[0055] A raiser assembly 512 is configured to vertically move and rotate a rotor 514 disposed in the processing volume 504. A supporting ring 516 is disposed on the rotor 514.

[0056] An edge ring 518 is supported by the supporting ring 516. A substrate 522 is disposed on the edge ring 518. The edge ring 518 and the substrate 522 are positioned above the radiant energy source 508 so that the radiant energy source 508 can heat both the substrate 522 and the edge ring 518. The edge ring 518 may be any edge rings described above according to embodiments of the present invention. In one embodiment, the edge ring 518 includes a surface area increasing structure 520 facing the radiant energy source 508.

[0057] During processing, the radiant energy source 508 is configured to rapidly heat the substrate 522 positioned on the edge ring 518, while the edge ring 518 heats an edge region of the substrate 522 by convection through direct contact. Edge rings according to embodiments of the present invention improve temperature uniformity across the substrate 522, particularly along the edge regions shadowed by the edge ring.

[0058] More detailed description of a thermal processing chamber may be found in United State Patent Application Publication 2009/0298300, which is herein incorporated by reference.

[0059] Experiments have shown the embodiments of the present invention improve greatly compared to traditional edge rings. Figure 6 includes plots showing comparison between traditional edge ring and edge rings according to embodiments of the present invention in term of edge ring deformation.

[0060] Curve 601 shows deformation of a traditional edge ring as shown in Figure 1A while supporting a substrate being heated to 1090 degrees C.

[0061] Curve 602 shows deformation of the edge ring shown in Figure 2A while supporting a substrate being heated to 1090 degrees C.

[0062] Curve 603 shows deformation of the edge ring shown in Figure 3A while supporting a substrate being heated to 1090 degrees C.

[0063] Curve 604 and curve 605 show deformation of the edge ring shown in Figure 3C while supporting substrates being heated to 1090 degrees C.

[0064] Figure 6 illustrates that edge rings according to embodiments of the present invention reduce edge ring deformation by about 80%.

[0065] Temperatures of the substrate being heated are also measured for the processes reflected in Figure 6.

[0066] For the traditional edge ring shown in Figure 1A, the times standard deviation of the temperature over the entire substrate is 16.22C while the substrate is heated to a target temperature of 1090 C.

[0067] For the edge ring shown in Figure 2A, the times standard deviation of the temperature over the entire substrate is 5.57 C while the substrate is heated to a target temperature of 1090 C.

[0068] For the edge ring shown in Figure 3A, the times standard deviation of the temperature over the entire substrate is 3.60 C while the substrate is heated to a target temperature of 1090 C.

[0069] For the edge ring shown in Figure 3C, the times standard deviation of the temperature over the entire substrate is 4.93 C while the substrate is heated to a target temperature of 1090 C.

[0070] Therefore, embodiments of the present invention greatly increase temperature uniformity during a thermal process.

[0071] Even though circular edge rings are described above, embodiments of the present invention may be applied to edge rings of other shapes, such as squared, rectangular, oval, etc. for processing substrates of different shapes.

[0072] Even though a thermal process and thermal processing chamber are described above, embodiments of the present invention may be used to any process and in any process chamber where a supporting structure or a substrate is exposed to a radiant energy.

[0073] While the foregoing is directed to embodiments of the present invention, other and further embodiments of the invention may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow.

What is Claimed is:

1. An edge ring for supporting a substrate in a processing chamber, comprising:
a ring shaped body defined by an inner edge, an outer edge, an upper side and a lower side, wherein the inner edge and outer edge are concentric about a central axis;
a lip extending radially inward from the inner edge of the ring shaped body, wherein at least a portion of an upper surface of the lip is configured to support a substrate around an outer edge of the substrate so that the substrate is substantially parallel to a major plane that is perpendicular to the central axis; and
one or more surface area increasing structures formed on at least one of the upper side or lower side of the ring shaped body.
2. The edge ring of claim 1, wherein the one or more surface area increasing structures comprises a fin extending from the lower side of the ring shaped body.
3. The edge ring of claim 2, wherein the fin forms a circular wall concentric to the inner edge and the outer edge, and the fin is positioned between the inner edge and the outer edge.
4. The edge ring of claim 3, wherein the upper surface of the lip is below an upper surface of the ring shaped body so that the lip and body form a recess for holding the substrate.
5. The edge ring of claim 4, wherein the fin is disposed at the inner edge of the ring shaped body, and the lip extends from the fin.
6. The edge ring of claim 2, wherein the lip is tilted at an angle relative to the major plane.

7. The edge ring of claim 1, wherein surface increasing structures are configured to face a radiant energy source.
8. A substrate support, comprising:
 - a body forming a closed loop, wherein the body is equal in width around the closed loop;
 - a lip extending inward from the body, wherein the lip has an upper surface configured to receive a substrate around an outer edge of the substrate, and the body surrounds the substrate when the substrate is disposed on the lip; and
 - one or more surface area increasing structures extending from an upper surface or a lower surface of the body.
9. The substrate support of claim 8, wherein the body is circular.
10. A chamber for processing a substrate, comprising:
 - a chamber body defining a processing volume, where the chamber body has a window formed therethrough;
 - a substrate support base disposed in the processing volume;
 - an energy source disposed outside the window to direct radiant energy towards the processing volume through the window; and
 - an edge ring of any one of claims 1-9 disposed on the substrate support base for supporting substrate thereon, wherein the one or more surface area increasing structure of the edge ring faces the energy source.
11. The chamber of claim 10, wherein the window is formed on a bottom of the chamber body, and the energy source is disposed below the edge ring.
12. A method for processing a substrate, comprising:
 - receiving a substrate on an edge ring of any one of claims 1-9 disposed in a processing chamber; and

radiating thermal energy from an energy source towards the substrate and the edge ring.

1/9

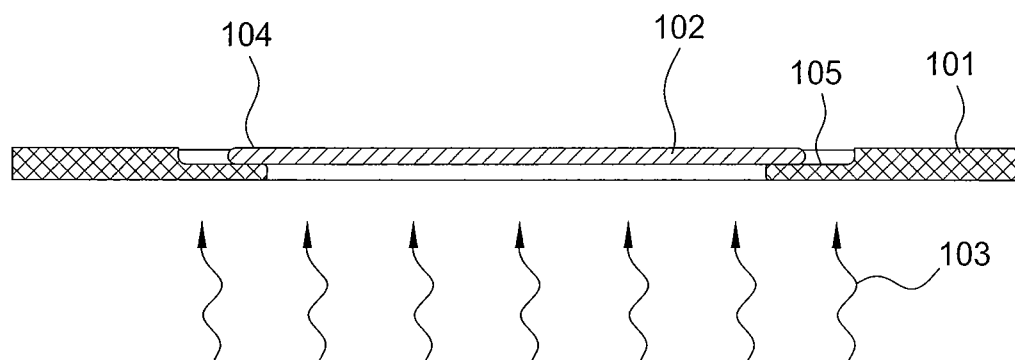


FIG. 1A
(PRIOR ART)

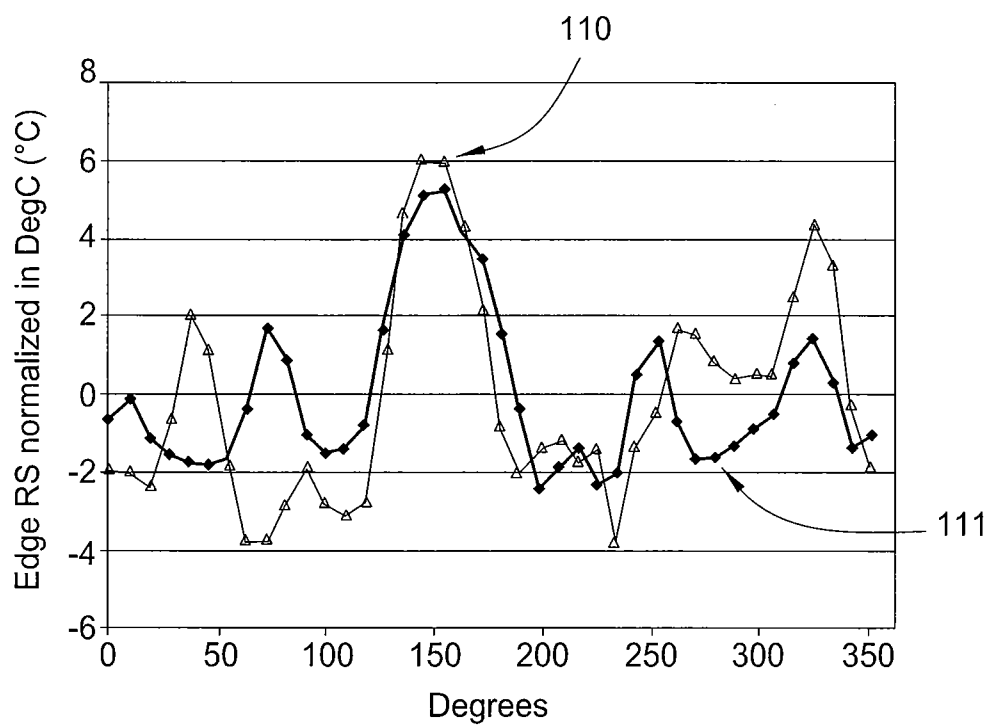


FIG. 1B
(PRIOR ART)

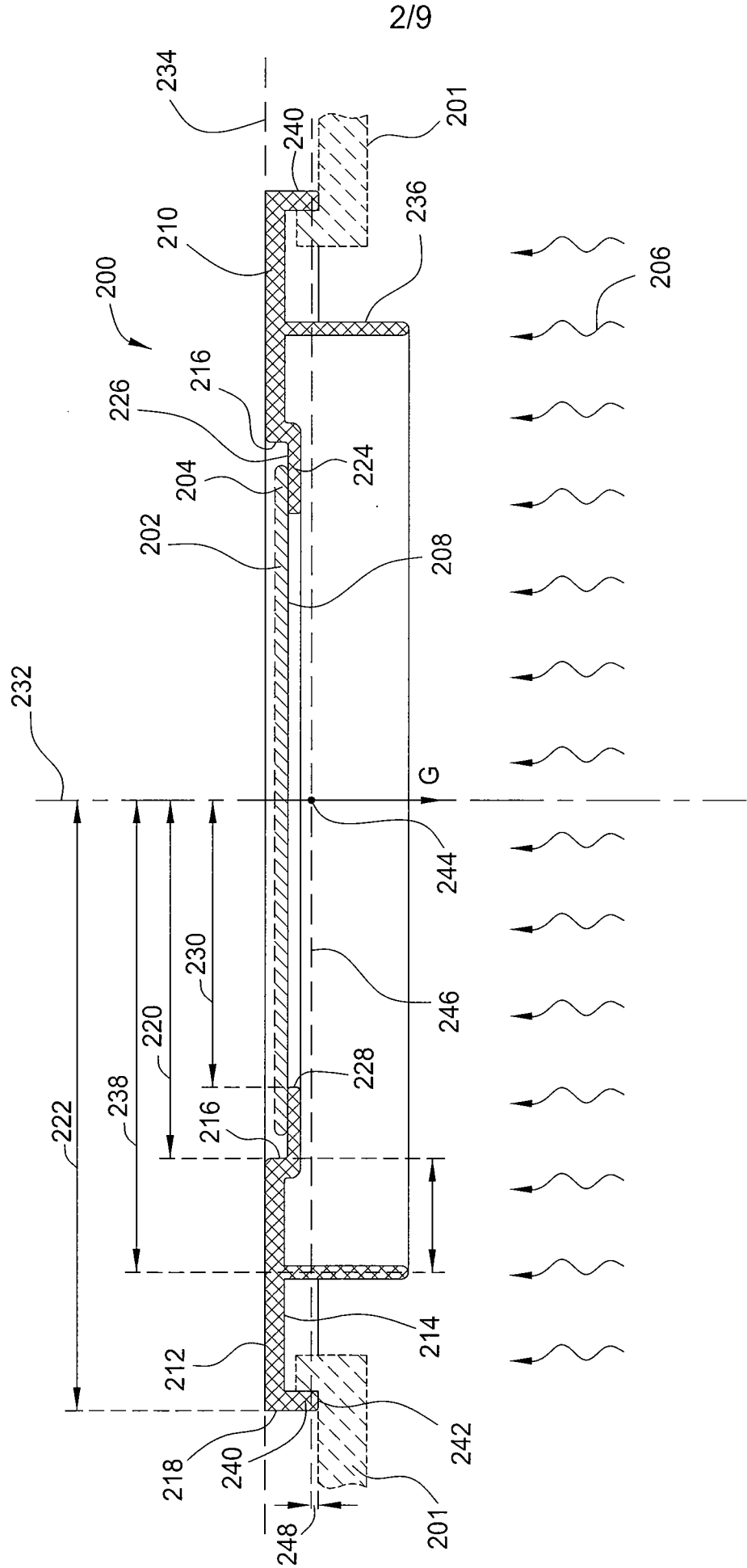


FIG. 2A

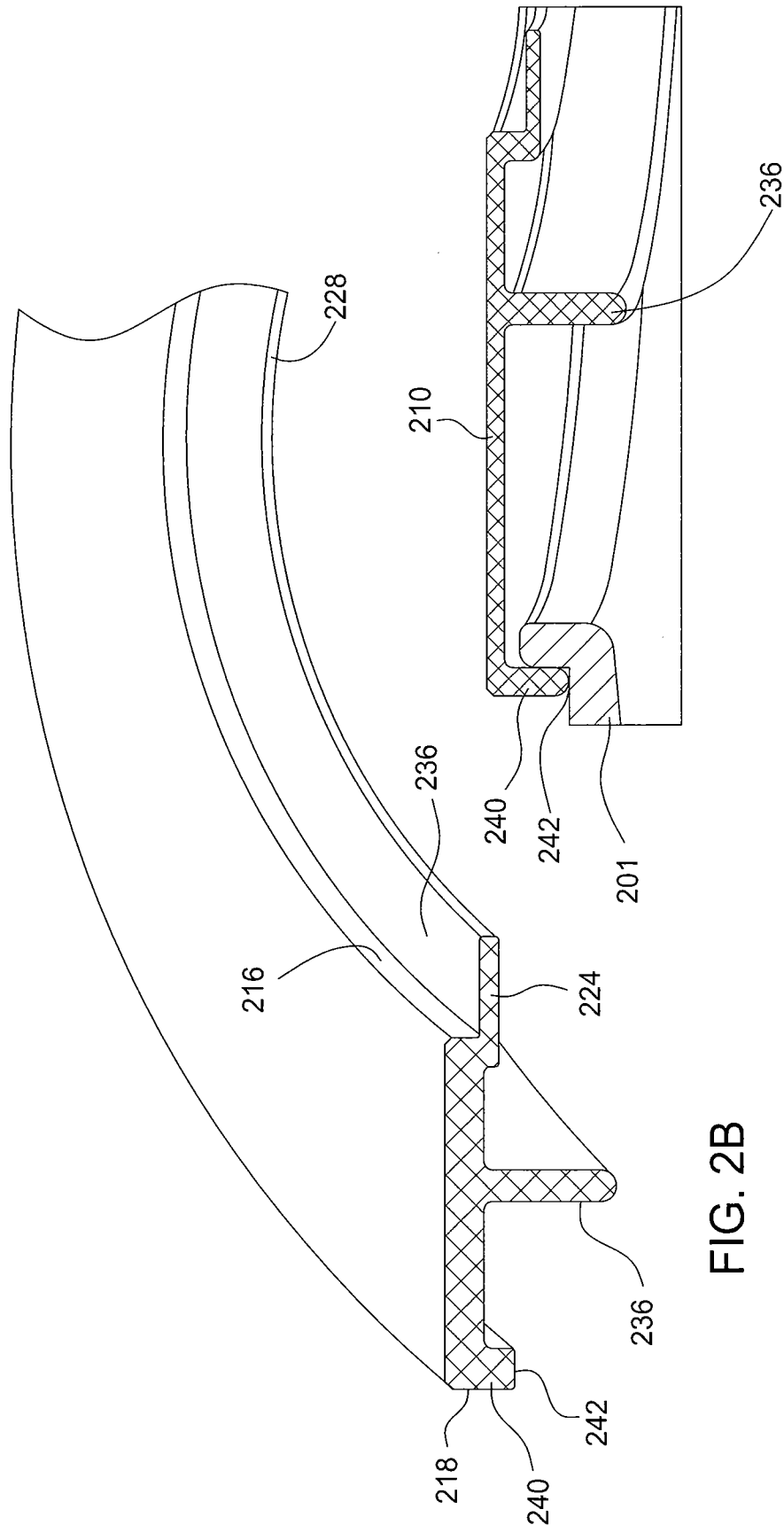


FIG. 2C

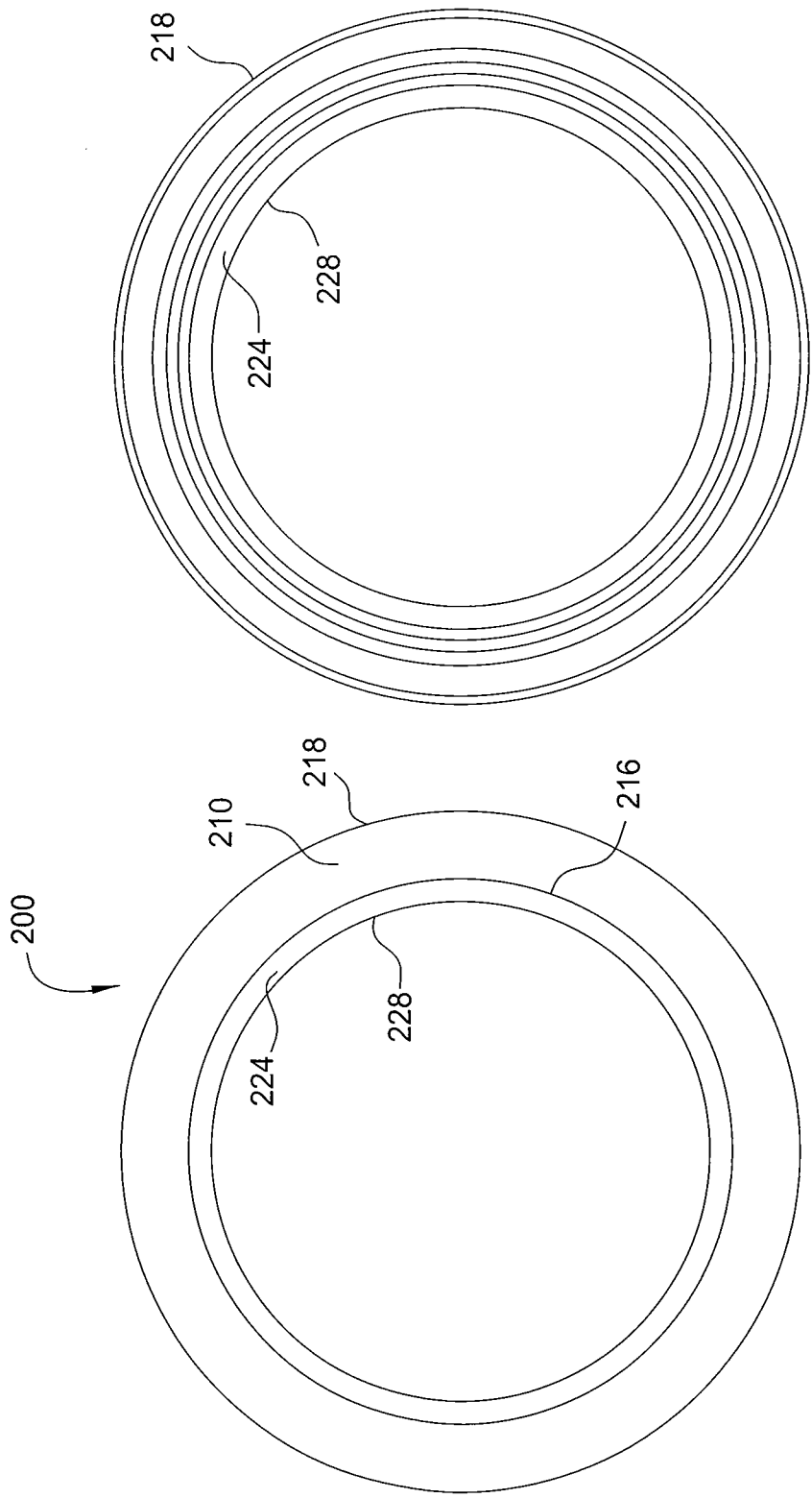


FIG. 2E

FIG. 2D

5/9

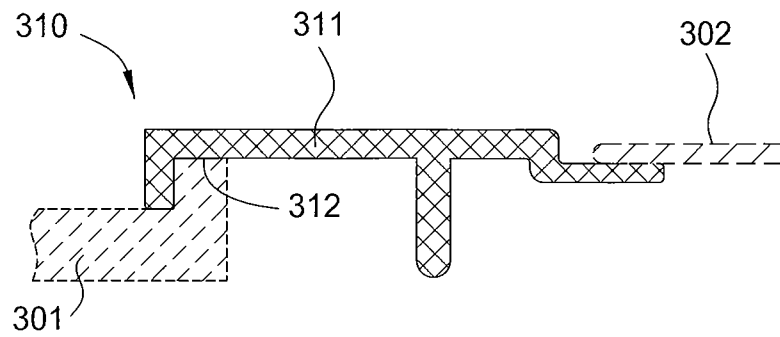


FIG. 3A

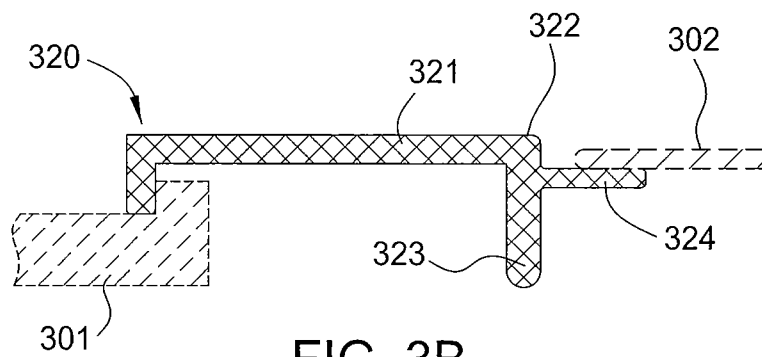


FIG. 3B

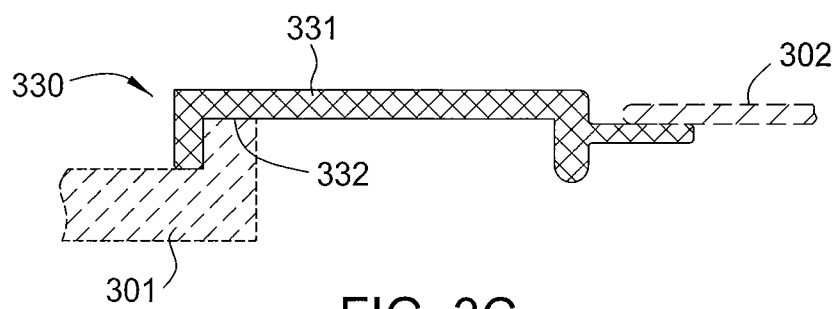


FIG. 3C

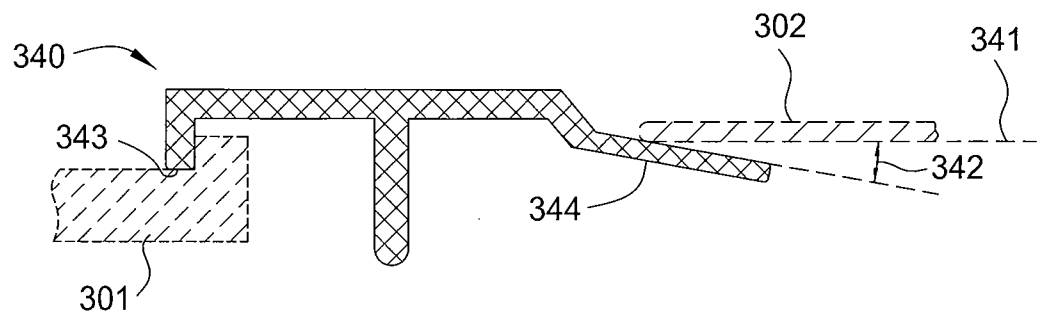


FIG. 3D

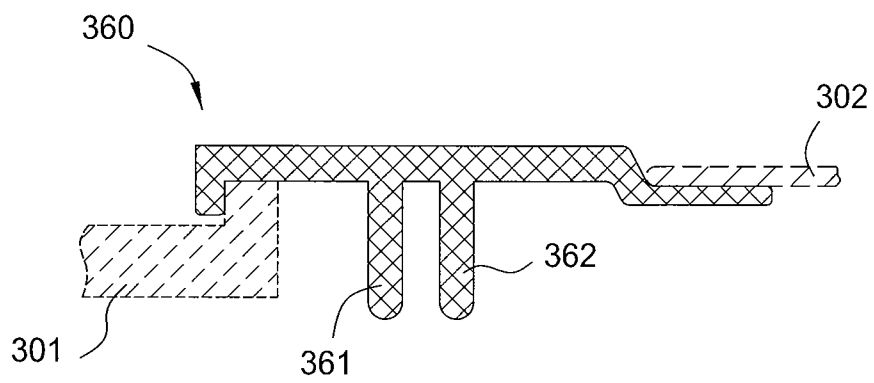
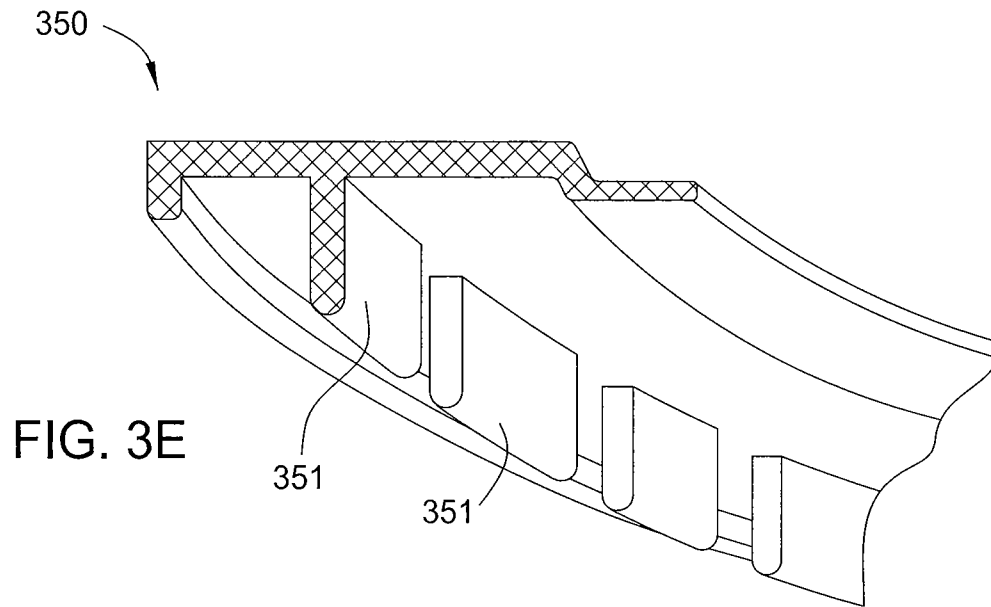


FIG. 3F

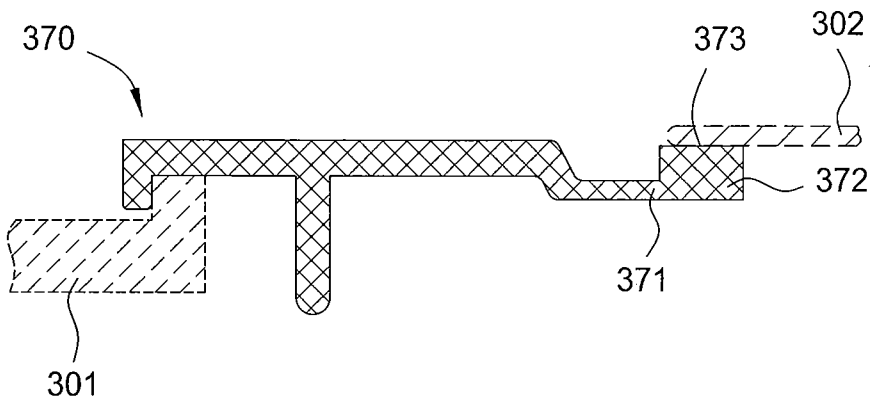


FIG. 3G

7/9

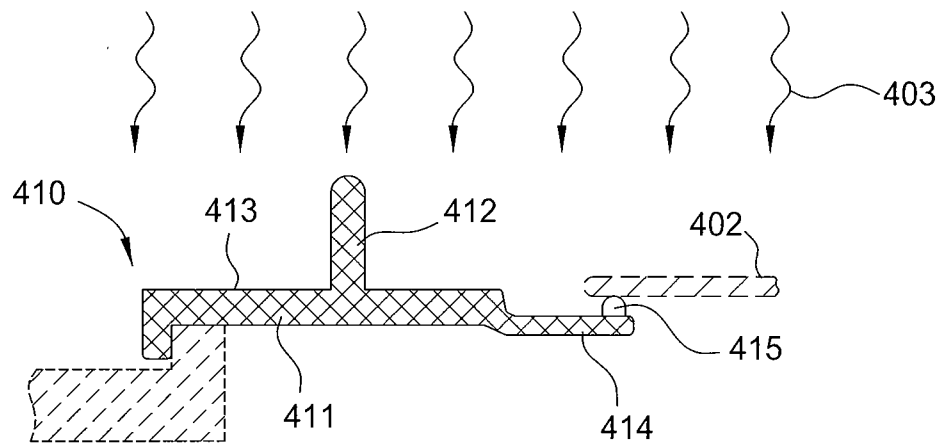


FIG. 4A

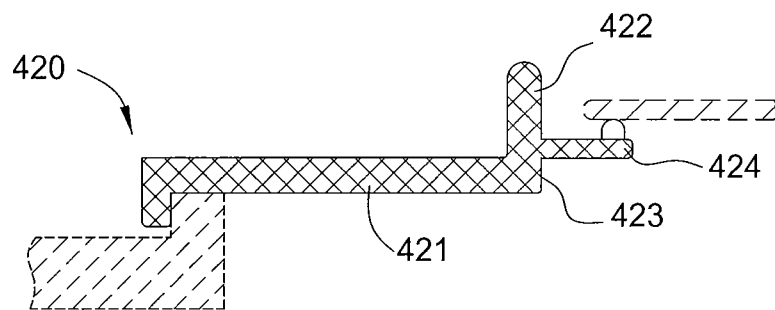


FIG. 4B

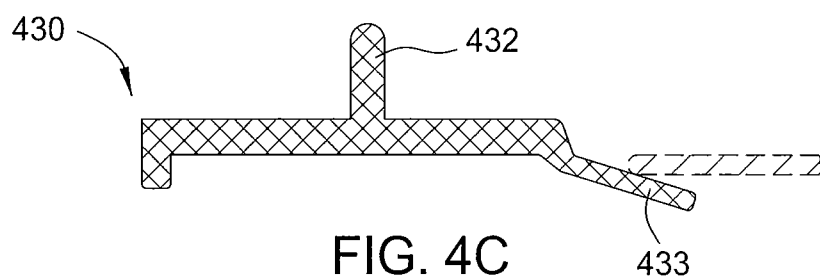


FIG. 4C

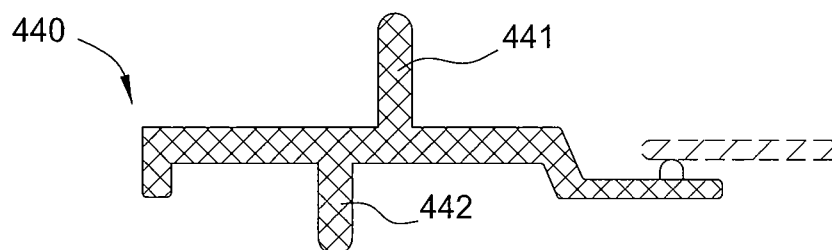


FIG. 4D

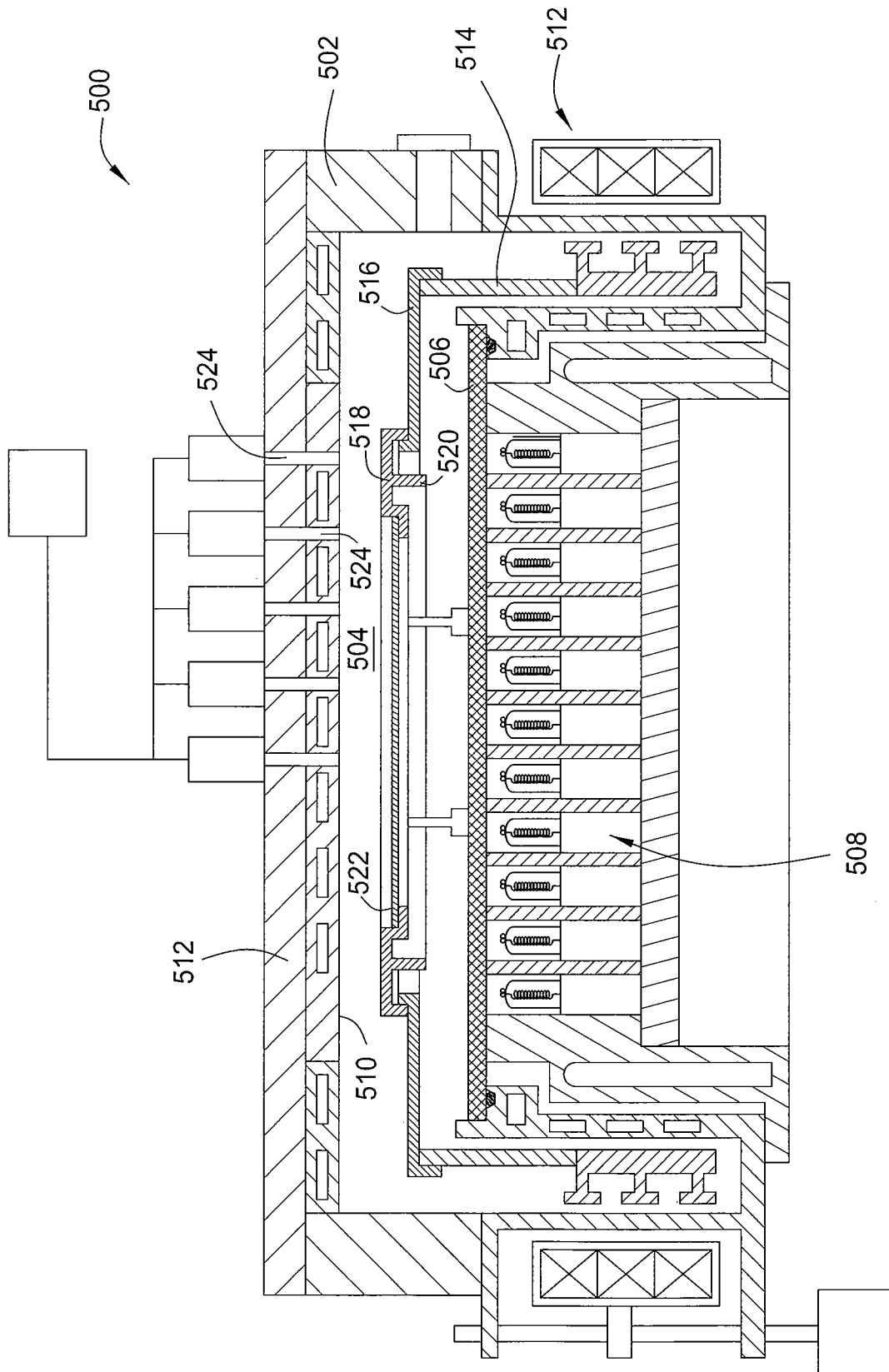


FIG. 5

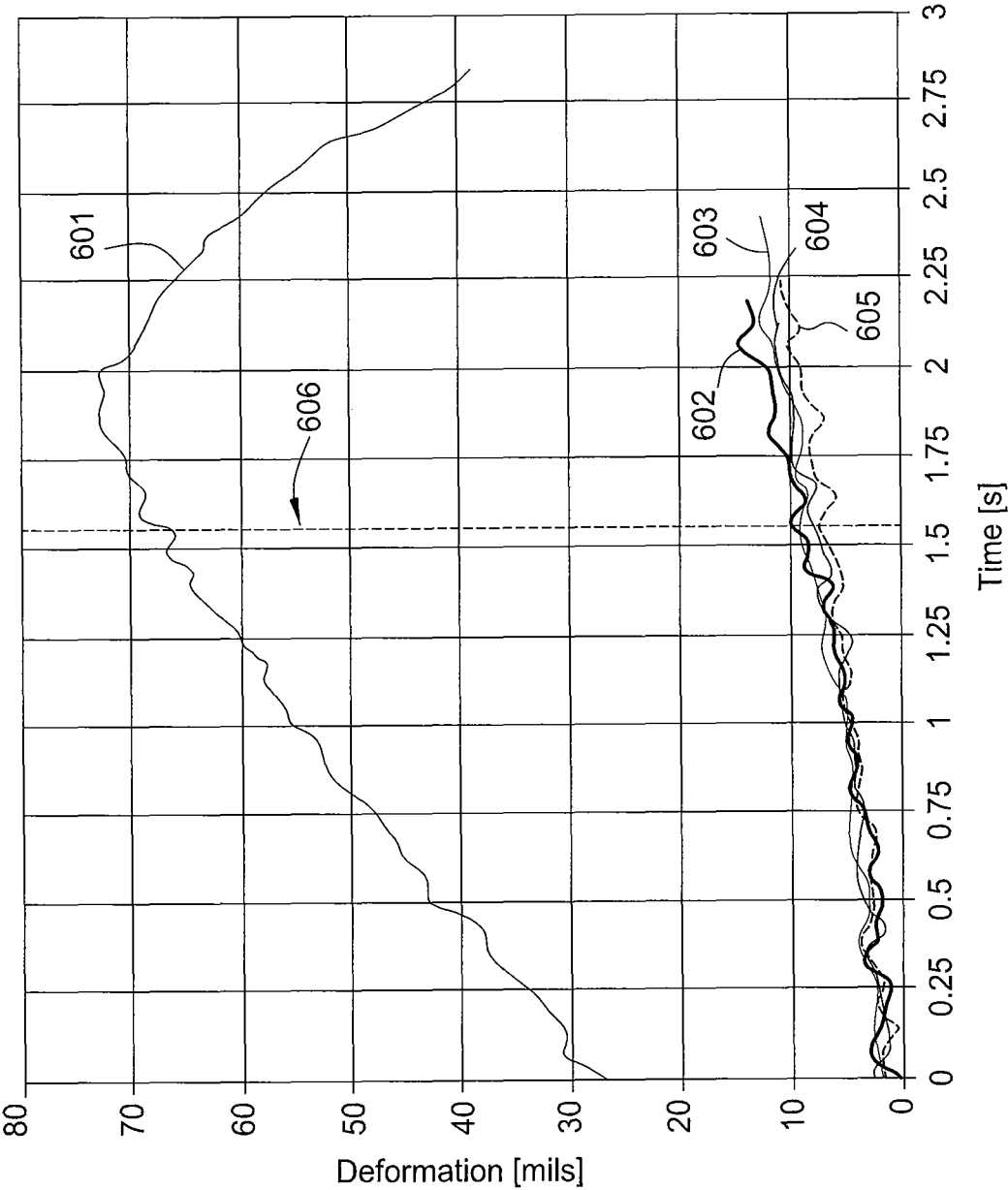


FIG. 6

A. CLASSIFICATION OF SUBJECT MATTER**H01L 21/683(2006.01)i, H01L 21/324(2006.01)i, H01L 21/02(2006.01)i**

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

H01L 21/683; H01L 21/3065; H05H 1/38; F27D 5/00; H05H 1/34

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Korean utility models and applications for utility models

Japanese utility models and applications for utility models

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

eKOMPASS(KIPO internal) & Keywords: chuck, susceptor, edge ring

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	JP 2004-289003 A (SEIKO EPSON CORP.) 14 October 2004 See paragraphs[0027-0028]; fig.4	1-12
A	US 6280183 B1 (MAYUR, ABHILASH et al.) 28 August 2001 See column 3 lines 4-10, 62-67; column 4 lines 27-31; column 5 lines 1-5; figs. 2,4.	1-12
A	WO 2010-030529 A3 (APPLIED MATERIALS, INC. et al.) 18 March 2010 See paragraphs[0028-0030]; fig.2.	1-12
A	US 6264467 B1 (LUE, BRIAN et al.) 24 July 2001 See column 4 lines 64-66; figs. 1-4,19.	1-12



Further documents are listed in the continuation of Box C.



See patent family annex.

* Special categories of cited documents:

"A" document defining the general state of the art which is not considered to be of particular relevance

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"P" document published prior to the international filing date but later than the priority date claimed

"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

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Date of the actual completion of the international search

07 MARCH 2012 (07.03.2012)

Date of mailing of the international search report

08 MARCH 2012 (08.03.2012)

Name and mailing address of the ISA/KR

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Authorized officer

Min Jung Yim

Telephone No. 82-42-481-3411



INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.

PCT/US2011/046008

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